METHOD AND APPARATUS FOR TRANSPORTING AND USING A SEMICONDUCTOR SUBSTRATE CARRIER

Abstract of the Disclosure

A carrier (200) having a side door (220) transports 300 millimeter semiconductor substrates (250) in a horizontal position. An airtight mini-environment is created by sealing mechanism (225) of the side door (220). Alignment features on the front of the carrier (440) and the process tool (430 align the carrier (440) to the tool (430). A gap (447) is formed between the carrier (440) and the tool (430)when the carrier is attached to the carrier. The side door (445) is lowered into the tool (430) out of the transport path of the semiconductor substrates contained in the carrier (440). Airflow from the tool (430) to the intermediate environment (420) to the fabrication environment (410) is from a cleaner environment to a less clean environment.

Figure 5 accompanies this abstract.